



PRODUCT / PROCESS CHANGE NOTIFICATION
Generic Copy

27-DEC-2000

SUBJECT: Product/Process Change Notification #10541

TITLE: 24/48 Lead TSSOP Transfer From Amkor, Korea To AIT,Indonesia.

EFFECTIVE DATE: 05-Apr-2001

AFFECTED CHANGE CATEGORY: Subcontractor Assembly Site

AFFECTED PRODUCT DIVISION: Logic Products Division

ADDITIONAL RELIABILITY DATA: Available
Contact your local ON Semiconductor Sales Office.
or Lyle Stewart <RJJ930@onsemi.com>

SAMPLES: Contact Below
Contact your local ON Semiconductor Sales Office.
or Richard Winer <R44132@onsemi.com>

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:
Contact Sales Office or Shahin Badiee <RA5032@onsemi.com>

DISCLAIMER:

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, please contact your local ON Semiconductor sales office.

DESCRIPTION AND PURPOSE:

24and 48 lead TSSOP devices are currently assembled at Amkor, Korea and tested at OSPI, Philippines. Transfer of this assembly and test capacity to AIT, Indonesia will provide increased manufacturing capacity in support of ON Semiconductor's increasing customer business requirements and continuous quality improvement.

QUALIFICATION PLAN:

See reliability data.



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RELIABILITY DATA SUMMARY:

Reliability data provided below is from AIT, Indonesia 48 lead TSSOP manufacturing dated Sept 2000 which represents current production. ON Semiconductor will perform qualification with LCX and VCX product during Q1 2001.

Test =====	Condition =====	Rej/SS =====
PRECONDITION to MSL1	85C/85% RH,168Hrs IR reflow 245C	
Lot A (WW1)		0/150
Lot B (WW2)		0/150
Lot C (WW3)		0/150
TEMP CYCLE	-65C to +150C @200/500/1000 cycles	
Lot A (WW1)	200 cycles	0/50
Lot A (WW1)	500 cycles	0/50
Lot A (WW1)	1000 cycles	0/50
Lot B (WW2)	200 cycles	0/50
Lot B (WW2)	500 cycles	0/50
Lot B (WW2)	1000 cycles	0/50
Lot C (WW3)	200 cycles	0/50
Lot C (WW3)	500 cycles	0/50
Lot C (WW3)	1000 cycles	0/50
HAST	JEDEC test method A110	
Lot A (WW1)	96Hrs	0/50
Lot B (WW2)	96Hrs	0/50
Lot C (WW3)	96Hrs	0/50
AUTOCLAVE	100%RH; 15 psig; 121C	
Lot A (WW1)	168Hrs	0/50
Lot B (WW2)	168Hrs	0/50
Lot C (WW3)	168Hrs	0/50

ELECTRICAL CHARACTERISTIC SUMMARY:

Meets all datasheet specifications and is consistent with current product. This assembly site packaging change does not impact electrical performance.

CHANGED PART IDENTIFICATION:

There is no physical change to the parts.
Only location code marking on the surface of the package will change as shown below:

Standard Part Marking: AWLYYWW

A: Assembly Site Location
WL: Wafer Lot#
YY: Year
WW: Work Week

Site Name: Assembly Site Location (A):
Amkor Sb
AIT Cp



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AFFECTED DEVICE LIST:

PART
74VCX162240DT
74VCX162240DTR
74VCX162244DT
74VCX162244DTR
74VCX162373DT
74VCX162373DTR
74VCX162374DT
74VCX162374DTR
74VCX16240DT
74VCX16240DTR
74VCX16244DT
74VCX16244DTR
74VCX16245DT
74VCX16245DTR
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74VCXH16245DTR
74VCXH16373DT
74VCXH16373DTR
74VCXH16374DT
74VCXH16374DTR
74VXR162245DT
74VXR162245DTR
MC74LCX16240DT
MC74LCX16240DTR2
MC74LCX16244DT
MC74LCX16244DTR2
MC74LCX16245DT
MC74LCX16245DTR2
MC74LCX16373DT
MC74LCX16373DTR2
MC74LCX16374DT
MC74LCX16374DTR2
MC74LCX646DT
MC74LCX646DTR2
MC74LCX652DT
MC74LCX652DTR2
MC74LVX4245DT
MC74LVX4245DTR2
MC74LVXC3245DT
MC74LVXC3245DTR2